

CLAIMS

1. A heater-equipped pusher for pushing a terminal of an electronic component to be tested in an electronic component handling apparatus into a contact portion of a test head, comprising:

a pusher main body which is capable of direct contact with the electronic component to be tested;

a heat absorbing and radiating body provided on said pusher main body;

a heater provided on said pusher main body to enable direct or indirect contact with the electronic component to be tested; and

a thermal insulating material provided between said pusher main body and said heater.

2. An electronic component handling apparatus which, in order to test an electronic component, is capable of pushing a terminal of an electronic component to be tested into a contact portion of a test head, comprising the heater-equipped pusher according to claim 1.

3. A temperature control method for controlling the temperature of an electronic component to be tested during the

testing of the electronic component in an electronic component handling apparatus, comprising:

cooling of the electronic component to be tested is performed by cooling a heat absorbing and radiating body to which the heat of the electronic component is transferred; and

heating of the electronic component to be tested is performed by a heater which is provided such that thermal resistance with said body increases.